

ITWS agenda version 4.13

Day 1 – Sep. 15, 2025

Start	Session	Duration
13:00	Registration and Coffee & Snacks Service <ul style="list-style-type: none"> Distribution of badges etc. 	45min
13:45	Opening Remarks to the ITWS 2025 <i>Organisational items</i> Speaker: Torsten Liese	15min
Keynote - AI In Our Industry For Testing (Host: Torsten Liese)		
14:00	Keynote: PDF Solutions, USA <i>AI For Manufacturing And Test, The New Frontier</i> Speaker: Marc Jacobs <ul style="list-style-type: none"> Q & A related to this session 	30min
Session Group A – Automation Processes & Test Solutions From Labs To Fabs (Host: Harald Berger)		
14:30	1st Session: CELADON, USA <i>“Innovative On-Wafer PIC Test Solutions for Labs to Fabs”</i> Speaker: Dalton Roehl <ul style="list-style-type: none"> Q & A related to this session 	30min
15:00	2nd Session: BOSCH Dresden, Germany + ACCRETECH Europe, Munich, Germany <i>“The Future of European Wafer Testing...an Automation Story”</i> Speaker: Michael Schatterny <ul style="list-style-type: none"> Q & A related to this session 	30min
Session Group B – Wafer Testing Efficiency - Total Costs Of Ownership (Host: Oliver Nagler)		
15:30	3rd Session: Delphon, USA + Gel-Pak, USA + CELADON, USA <i>“Extending Parametric Probecard Lifetime To Reduce Overall Cost Of Test For Very Small Pad Probing”</i> Speaker: Garrett Tranquillo (CELADON) & Victoria Tran (Gel-Pak) <ul style="list-style-type: none"> Q & A related to this session 	30min
16:00	Coffee Break & Poster Sessions	60min
17:00	4th Session: CELADON, USA + HTT Group, Germany <i>“Recipe for Best-in-Class Production Parametric Testing”</i> Speaker: Karen Armendariz (CELADON) & Janina Freyboth (HTT) <ul style="list-style-type: none"> Q & A related to this session 	30min
Session Group C – New Innovative Probing & Testing Solutions (Host: TBD)		
17:30	5th Session: ATV Systems GmbH, Germany <i>“1 - Integrated solution for highly stable full wafer reliability testing of microLEDs. 2 - VersaJet, an anti-arcing solution from Celadon”</i> Speaker: Ian Cheng <ul style="list-style-type: none"> Q & A related to this session 	30min
18:00	6th Session: Dectris AG, Switzerland <i>“Large CMOS Chips Tested on Expanded Frame with Single Die Theta Alignment”</i> Speaker: Pascal Jud <ul style="list-style-type: none"> Q & A related to this session 	30min
19:00	Dinner	Open end

Day 2 – Sep. 16, 2025

Start	Session	Duration
Session Group D – Wafer Testing @ The Limits (Testing @ Hot & Cold Temperature) (Host: TBD)		
9:15	7th Session: University of Basel, Switzerland <i>“Cryonic testing Of Quantum Electronic Devices”</i> Speaker: Clemens Spinnler <ul style="list-style-type: none"> Q & A related to this session 	30min
9:45	8th Session: Session: GlobalFoundries Dresden, + HTT Group, Germany <i>“Probing Challenges for High Temperature Testing of MRAM Device”</i> Speaker: Alexander Wittig (GlobalFoundries) & Mike Strech (HTT) <ul style="list-style-type: none"> Q & A related to this session 	30min
10:15	Coffee Break & Poster Sessions	45min
11:00	9th Session: ERS Electronic GmbH, Germany <i>“Localized Thermal Management for Wafer-Level Testing of High-Power AI and GPU Chips”</i> Speaker: Klaudiusz Holeczek & Klemens Reitingner Q & A related to this session	30min
Session Group E – Wafer Testing @ The Limits (High Power/Ultrafast/High Parallelism) (Host: Rainer Gaggl)		
11:30	10th Session: Infineon Technologies Dresden + JEM Europe, France <i>“...introduce productive dynamic die-level test (DLT) for SiC FETs, esp. >1kA short-circuit test”</i> Speaker: Andreas Gneupel (Infineon) & Joe Mai (JEM) Q & A related to this session	30min
12:00	11th Session: T.I.P.S. Villach, Austria <i>“KGD – Ultrafast Dynamic Power Device Probing”</i> Speaker: Sebastian Salbrechter <ul style="list-style-type: none"> Q & A related to this session 	30min
12:30	12th Session: MPI, Taiwan <i>“Structural and Electrical Optimization of Large-Area MLC Probe Card”</i> Speaker: Bobby Chen Q & A related to this session	30min
13:00	Presentation Awards / Summary of ITWS 2025 Speaker: Torsten Liese	30min
13:30	End of Workshop	